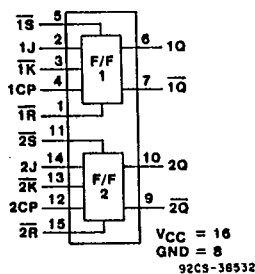


Advanced Information

CD54/74AC109, CD54/74AC112 CD54/74ACT109, CD54/74ACT112

T-46-07-07



CD54/74AC/ACT109
FUNCTIONAL DIAGRAM

Type Features:

- Buffered inputs
- Typical propagation delay:
4.8 ns @ $V_{CC} = 5\text{ V}$, $T_A = 25^\circ\text{C}$, $C_L = 50\text{ pF}$

Dual "J-K" Flip-Flop with Set and Reset

CD54/74AC/ACT109 - Positive-Edge-Triggered (J, K)

CD54/74AC/ACT112 - Negative-Edge-Triggered (J, K)

The RCA CD54/74AC109 and CD54/74AC112 and the CD54/74ACT109 and CD54/74ACT112 dual "J-K" flip-flops with set and reset use the RCA ADVANCED CMOS technology. These flip-flops have independent J, K (or K), Set, Reset, and Clock inputs and Q and $\bar{Q}$ outputs. The CD54/74AC/ACT112 changes state on the negative-going transition of the clock pulse. The CD54/74AC/ACT109 changes state on the positive-going transition of the clock. Set and Reset are accomplished asynchronously by low-level inputs.

The CD74AC/ACT109 and CD74AC/ACT112 are supplied in 16-lead dual-in-line plastic packages (E suffix) and in 16-lead dual-in-line small-outline plastic packages (M suffix). Both package types are operable over the following temperature ranges: Commercial (0 to 70°C); Industrial (-40 to $+85^\circ\text{C}$); and Extended Industrial/Military (-55 to $+125^\circ\text{C}$).

The CD54AC/ACT109 and CD54AC/ACT112, available in chip form (H suffix), are operable over the -55 to $+125^\circ\text{C}$ temperature range.

Family Features:

- Exceeds 2-kV ESD Protection - MIL-STD-883, Method 3015
- SCR-Latchup-resistant CMOS process and circuit design
- Speed of bipolar FAST[®]/AS/S with significantly reduced power consumption
- Balanced propagation delays
- AC types feature 1.5-V to 5.5-V operation and balanced noise immunity at 30% of the supply
- $\pm 24\text{-mA}$ output drive current
 - Fanout to 15 FAST[®] ICs
 - Drives 50-ohm transmission lines

*FAST is a Registered Trademark of Fairchild Semiconductor Corp.

CD54/74AC/ACT109 TRUTH TABLE

INPUTS					OUTPUTS	
$\bar{S}$	$\bar{R}$	CP	J	$\bar{K}$	Q	$\bar{Q}$
L	H	X	X	X	H	L
H	L	X	X	X	L	H
L	L	X	X	X	H*	H*
H	H		L	L	L	H
H	H		H	L	TOGGLE	
H	H		L	H	NO CHANGE	
H	H		H	H	H	L
H	H	L	X	X	NO CHANGE	

*Unpredictable and unstable condition if both $\bar{S}$ and $\bar{R}$ go high simultaneously.

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File Number 1967

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Technical Data

CD54/74AC109, CD54/74AC112
CD54/74ACT109, CD54/74ACT112

T-46-07-07

CD54/74AC/ACT112 TRUTH TABLE

INPUTS					OUTPUTS	
$\bar{S}$	$\bar{R}$	$\bar{CP}$	J	K	Q	$\bar{Q}$
L	H	X	X	X	H	L
H	L	X	X	X	L	H
L	L	X	X	X	H*	H*
H	H		L	L	NO CHANGE	
H	H		H	L	H	L
H	H		L	H	L	H
H	H		H	H	TOGGLE	
H	H	H	X	X	NO CHANGE	

*Output states unpredictable if $\bar{S}$ and $\bar{R}$ go High simultaneously after both being Low at the same time.

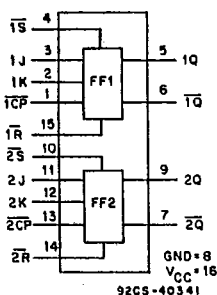
H = High steady state

L = Low steady state

X = Irrelevant

= High-to-Low transition

= Low-to-High transition


CD54/74AC/ACT112
FUNCTIONAL DIAGRAM
MAXIMUM RATINGS, Absolute-Maximum Values:

DC SUPPLY-VOLTAGE (V_{CC})	-0.5 to 6 V
DC INPUT DIODE CURRENT, I_{IK} (for $V_I < -0.5$ V or $V_I > V_{CC} + 0.5$ V)	± 20 mA
DC OUTPUT DIODE CURRENT, I_{OK} (for $V_O < -0.5$ V or $V_O > V_{CC} + 0.5$ V)	± 50 mA
DC OUTPUT SOURCE OR SINK CURRENT per Output Pin, I_O (for $V_O > -0.5$ V or $V_O < V_{CC} + 0.5$ V)	± 50 mA
DC V_{CC} or GROUND CURRENT (I_{CC} or I_{GND})	± 100 mA*
POWER DISSIPATION PER PACKAGE (P_D):	
For $T_A = -55$ to $+100^\circ\text{C}$ (PACKAGE TYPE E)	500 mW
For $T_A = +100$ to $+125^\circ\text{C}$ (PACKAGE TYPE E)	Derate Linearly at 8 mW/ $^\circ\text{C}$ to 300 mW
For $T_A = -55$ to $+70^\circ\text{C}$ (PACKAGE TYPE M)	400 mW
For $T_A = +70$ to $+125^\circ\text{C}$ (PACKAGE TYPE M)	Derate Linearly at 6 mW/ $^\circ\text{C}$ to 70 mW
OPERATING-TEMPERATURE RANGE (T_A)	-55 to $+125^\circ\text{C}$
STORAGE TEMPERATURE (T_{stg})	-65 to $+150^\circ\text{C}$
LEAD TEMPERATURE (DURING SOLDERING):	
At distance $1/16 \pm 1/32$ in. (1.59 $\pm$ 0.79 mm) from case for 10 s maximum	$+265^\circ\text{C}$
Unit inserted into PC board min. thickness $1/16$ in. (1.59 mm) with solder contacting lead tips only	$+300^\circ\text{C}$

*For up to 4 outputs per device; add ± 25 mA for each additional output.

RECOMMENDED OPERATING CONDITIONS:

For maximum reliability, normal operating conditions should be selected so that operation is always within the following ranges:

CHARACTERISTICS	LIMITS		UNITS
	MIN.	MAX.	
Supply-Voltage Range, V_{CC} †:			
(For T_A = Full Package-Temperature Range)			
AC Types	1.5	5.5	V
ACT Types	4.5	5.5	V
DC Input or Output Voltage, V_I, V_O	0	V_{CC}	V
Operating Temperature, T_A	-55	+125	$^\circ\text{C}$
Input Rise and Fall Slew Rate, dV/dt			
at 1.5 V to 3 V (AC Types)	0	50	ns/V
at 3.6 V to 5.5 V (AC Types)	0	20	ns/V
at 4.5 V to 5.5 V (ACT Types)	0	10	ns/V

†Unless otherwise specified, all voltages are referenced to ground.

CD54/74AC109, CD54/74AC112 CD54/74ACT109, CD54/74ACT112

STATIC ELECTRICAL CHARACTERISTICS: AC Series

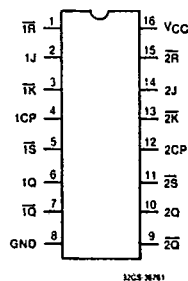
T-46-07-07

CHARACTERISTICS	TEST CONDITIONS		V _{CC} (V)	AMBIENT TEMPERATURE (T _A) - °C						UNITS	
				+25		-40 to +85		-55 to +125			
	V _I (V)	I _O (mA)		MIN.	MAX.	MIN.	MAX.	MIN.	MAX.		
High-Level Input Voltage	V _{IH}		1.5 3 5.5	1.2 2.1 3.85	— — —	1.2 2.1 3.85	— — —	1.2 2.1 3.85	— — —	V	
Low-Level Input Voltage	V _{IL}		1.5 3 5.5	— — —	0.3 0.9 1.65	— — —	0.3 0.9 1.65	— — —	0.3 0.9 1.65	V	
High-Level Output Voltage	V _{OH}	V _{IH} or V _{IL} #,*	-0.05	1.5	1.4	—	1.4	—	1.4	—	V
			-0.05	3	2.9	—	2.9	—	2.9	—	
			-0.05	4.5	4.4	—	4.4	—	4.4	—	
			-4	3	2.58	—	2.48	—	2.4	—	
			-24	4.5	3.94	—	3.8	—	3.7	—	
			-75	5.5	—	—	3.85	—	—	—	
Low-Level Output Voltage	V _{OL}	V _{IH} or V _{IL} #,*	-50	5.5	—	—	—	—	3.85	—	V
			0.05	1.5	—	0.1	—	0.1	—	0.1	
			0.05	3	—	0.1	—	0.1	—	0.1	
			0.05	4.5	—	0.1	—	0.1	—	0.1	
			12	3	—	0.36	—	0.44	—	0.5	
			24	4.5	—	0.36	—	0.44	—	0.5	
Input Leakage Current	I _I	V _{CC} or GND	75	5.5	—	—	—	1.65	—	μA	
			50	5.5	—	—	—	—	—		1.65
Quiescent Supply Current, FF	I _{CC}	V _{CC} or GND	0	5.5	—	4	—	40	—	80	μA

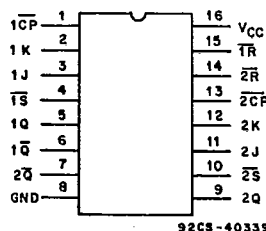
#Test one output at a time for a 1-second maximum duration. Measurement is made by forcing current and measuring voltage to minimize power dissipation.

*Test verifies a minimum 50-ohm transmission-line-drive capability at +85°C, 75 ohms at +125°C.

TERMINAL ASSIGNMENT DIAGRAMS



CD54/74AC/ACT109



CD54/74AC/ACT112

Technical Data

CD54/74AC109, CD54/74AC112
CD54/74ACT109, CD54/74ACT112

T-46-07-07

STATIC ELECTRICAL CHARACTERISTICS: ACT Series

CHARACTERISTICS		TEST CONDITIONS		V _{CC} (V)	AMBIENT TEMPERATURE (T _A) - °C						UNITS
					+25		-40 to +85		-55 to +125		
		V _I (V)	I _O (mA)		MIN.	MAX.	MIN.	MAX.	MIN.	MAX.	
High-Level Input Voltage	V _{IH}			4.5 to 5.5	2	—	2	—	2	—	V
Low-Level Input Voltage	V _{IL}			4.5 to 5.5	—	0.8	—	0.8	—	0.8	V
High-Level Output Voltage	V _{OH}	V _{IH} or V _{IL} #, *	-0.05	4.5	4.4	—	4.4	—	4.4	—	V
			-24	4.5	3.94	—	3.8	—	3.7	—	
			-75	5.5	—	—	3.85	—	—	—	
			-50	5.5	—	—	—	—	3.85	—	
Low-Level Output Voltage	V _{OL}	V _{IH} or V _{IL} #, *	0.05	4.5	—	0.10	—	0.10	—	0.10	V
			24	4.5	—	0.36	—	0.44	—	0.50	
			75	5.5	—	—	—	1.65	—	—	
			50	5.5	—	—	—	—	—	1.65	
Input Leakage Current	I _I	V _{CC} or GND		5.5	—	±0.1	—	±1	—	±1	μA
Quiescent Supply Current, FF	I _{CC}	V _{CC} or GND	0	5.5	—	4	—	40	—	80	μA
Additional Supply Current per Input Pin TTL Inputs High 1 Unit Load	ΔI _{CC}	V _{CC} -2.1		4.5 to 5.5	—	2.4	—	2.8	—	3	mA

#Test one output at a time for a 1-second maximum duration. Measurement is made by forcing current and measuring voltage to minimize power dissipation.

*Test verifies a minimum 50-ohm transmission-line-drive capability at +85°C, 75 ohms at +125°C.

ACT INPUT LOADING TABLE

INPUT	UNIT LOADS*	
	109	112
J, CP, $\overline{CP}$	1	1
K	—	0.53
$\overline{K}$	0.53	—
$\overline{S}$, $\overline{R}$	0.58	0.58

*Unit load is ΔI_{CC} limit specified in Static Characteristics Chart, e.g., 2.4 mA max. @ 25°C.

CD54/74AC109, CD54/74AC112

CD54/74ACT109, CD54/74ACT112

PREREQUISITE FOR SWITCHING: AC Series

T-46-07-07

CHARACTERISTICS	SYMBOL	V _{CC} (V)	AMBIENT TEMPERATURE (T _A) - °C				UNITS
			-40 to +85		-55 to +125		
			MIN.	MAX.	MIN.	MAX.	
Maximum CP, ($\overline{CP}$) Frequency 109	f _{max}	1.5 3.3* 5†	9 81 114	— — —	8 71 100	— — —	MHz
112	f _{max}	1.5 3.3 5	9 81 114	— — —	8 71 100	— — —	MHz
CP, ($\overline{CP}$) Pulse Width	t _w	1.5 3.3 5	55 6 4.4	— — —	63 7 5	— — —	ns
R, S Pulse Width	t _w	1.5 3.3 5	49 5.5 3.9	— — —	56 6.3 4.5	— — —	ns
Setup Time J, K to CP 109	t _{su}	1.5 3.3 5	61 6.8 4.8	— — —	69 7.7 5.5	— — —	ns
J, K to $\overline{CP}$ 112	t _{su}	1.5 3.3 5	44 4.9 3.5	— — —	50 5.6 4	— — —	ns
Hold Time J, K to CP 109	t _h	1.5 3.3 5	0 0 0	— — —	0 0 0	— — —	ns
J, K to $\overline{CP}$ 112	t _h	1.5 3.3 5	0 0 0	— — —	0 0 0	— — —	ns
Removal Time R, S to CP, ($\overline{CP}$)	t _{REM}	1.5 3.1 5	27 3.1 2.2	— — —	31 3.5 2.5	— — —	ns

*3.3 V: min. is @ 3 V

†5 V: min is @ 4.5 V

SWITCHING CHARACTERISTICS: AC Series; t_r, t_f = 3 ns, C_L = 50 pF

CHARACTERISTICS	SYMBOL	V _{CC} (V)	AMBIENT TEMPERATURE (T _A) - °C				UNITS
			-40 to +85		-55 to +125		
			MIN.	MAX.	MIN.	MAX.	
Propagation Delays: CP, (CP) to Q, Q̄	t _{PLH} t _{PHL}	1.5 3.3* 5†	— 3.7 2.7	117 13.1 9.4	— 3.6 2.6	129 14.4 10.3	ns
S̄, R to Q, Q̄	t _{PLH} t _{PHL}	1.5 3.3 5	— 4.4 3.2	139 15.5 11.1	— 4.3 3.1	153 17.1 12.2	ns
Power Dissipation Capacitance	C _{PD} §	—	56 Typ.		56 Typ.		pF
Input Capacitance	C _I	—	—	10	—	10	pF

*3.3 V: min. is @ 3.6 V
max. is @ 3 V†5 V: min. is @ 5.5 V
max. is @ 4.5 V§C_{PD} is used to determine the dynamic power consumption, per flip-flop.P_O = C_{PD}V_{CC}² f_i + Σ (C_LV_{CC}² f_o) where f_i = input frequencyf_o = output frequencyC_L = output load capacitanceV_{CC} = supply voltage.

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Technical Data

CD54/74AC109, CD54/74AC112
CD54/74ACT109, CD54/74ACT112

T-46-07-07

PREREQUISITE FOR SWITCHING: ACT Series

CHARACTERISTICS	SYMBOL	V _{CC} (V)	AMBIENT TEMPERATURE (T _A) - °C				UNITS
			-40 to +85		-55 to +125		
			MIN.	MAX.	MIN.	MAX.	
Maximum CP, ($\overline{CP}$) Frequency 109	f _{max}	5*	114	—	100	—	MHz
112			114	—	100	—	
CP, ($\overline{CP}$) Pulse Width	t _w	5	4.4	—	5	—	ns
R, $\overline{S}$ Pulse Width	t _w	5	4.8	—	5.5	—	ns
Setup Time J, K to CP (109)	t _{su}	5	4.8	—	5.5	—	ns
J, K to $\overline{CP}$ (112)			3.5	—	4	—	
Hold Time J, K to CP (109)	t _H	5	0	—	0	—	ns
J, K to $\overline{CP}$ (112)			1	—	1	—	
Removal Time R, $\overline{S}$ to CP, ($\overline{CP}$)	t _{rem}	5	2.2	—	2.5	—	ns

*5 V: min. is @ 4.5 V

SWITCHING CHARACTERISTICS: ACT Series; t_r, t_f = 3 ns, C_L = 50 pF

CHARACTERISTICS	SYMBOL	V _{CC} (V)	AMBIENT TEMPERATURE (T _A) - °C				UNITS
			-40 to +85		-55 to +125		
			MIN.	MAX.	MIN.	MAX.	
Propagation Delays CP, (CP) to Q, Q	t _{PLH} t _{PHL}	5*	2.7	9.4	2.6	10.3	ns
S, R, to Q, Q	t _{PLH} t _{PHL}	5	3.2	11.1	3.1	12.2	ns
Power Dissipation Capacitance	C _{PD} §	—	56 Typ.		56 Typ.		pF
Input Capacitance	C _I	—	—	10	—	10	pF

*5 V: min. is @ 5.5 V
max. is @ 4.5 V§C_{PD} is used to determine the dynamic power consumption, per flip-flop.
$$P_D = C_{PD} V_{CC}^2 f_i + \sum (C_L V_{CC}^2 f_o) + V_{CC} \Delta I_{CC}$$

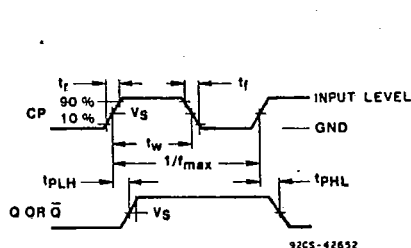
where f_i = input frequency
f_o = output frequency
C_L = output load capacitance
V_{CC} = supply voltage.

CD54/74AC109, CD54/74AC112

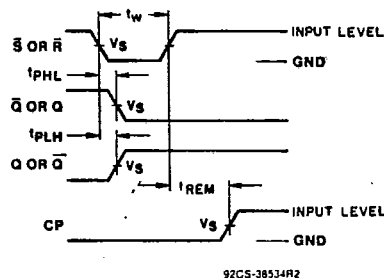
CD54/74ACT109, CD54/74ACT112

CD54/74AC/ACT109 Waveforms

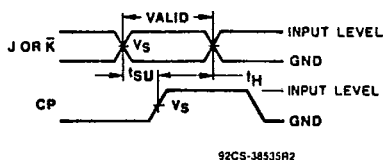
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Clock to output delays and clock pulse width.

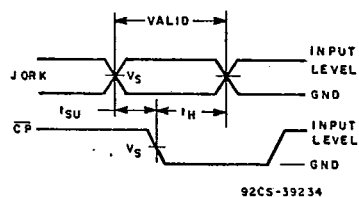
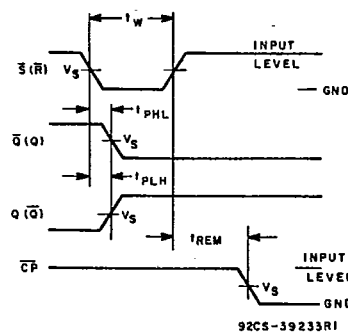
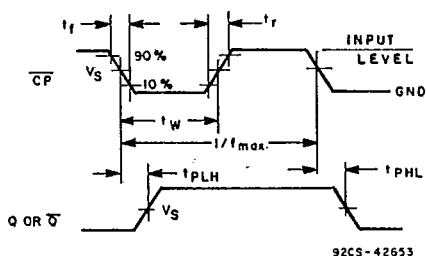


Reset or Set prerequisite and propagation delays.

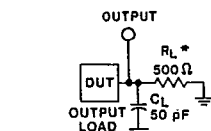


Data setup and hold times.

CD54/74AC/ACT112 Waveforms



Propagation delay times, and setup and hold times.



*FOR AC SERIES ONLY: WHEN
V_{CC} = 1.5 V, R_L = 1 kΩ

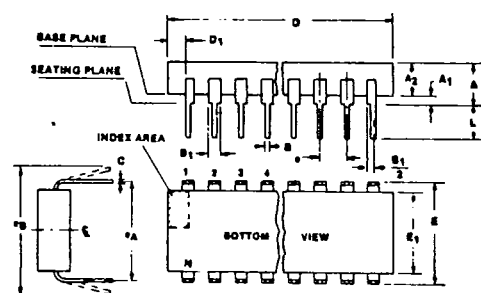
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Test circuit.

	CD54/74AC	CD54/74ACT
Input Level	V _{CC}	3 V
Input Switching Voltage, V _s	0.5 V _{CC}	1.5 V
Output Switching Voltage, V _s	0.5 V _{CC}	0.5 V _{CC}

Dual-In-Line Plastic Packages

T-90-20

(E) Suffix (JEDEC MS-001-AC)
14-Lead Dual-In-Line Plastic Package

SYMBOL	INCHES		MILLIMETERS		NOTES
	MIN.	MAX.	MIN.	MAX.	
A	—	0.210	—	5.33	9
A ₁	0.015	—	0.39	—	9
A ₂	0.115	0.195	2.93	4.95	
B	0.014	0.022	0.356	0.558	
B ₁	0.045	0.070	1.15	1.77	3
C	0.008	0.015	0.204	0.381	
D	0.725	0.795	18.42	20.19	4
D ₁	0.005	—	0.13	—	12
E	0.300	0.325	7.62	8.25	5
E ₁	0.240	0.280	6.10	7.11	6, 7
e	0.100 BSC		2.54 BSC		8
e _A	0.300 BSC		7.62 BSC		9
e _B	—	0.430	—	10.92	10
L	0.115	0.160	2.93	4.06	9
N	14		14		11

92CS-39901

(E) Suffix (JEDEC MS-001-AA)
16-Lead Dual-In-Line Plastic Package

SYMBOL	INCHES		MILLIMETERS		NOTES
	MIN.	MAX.	MIN.	MAX.	
A	—	0.210	—	5.33	9
A ₁	0.015	—	0.39	—	9
A ₂	0.115	0.195	2.93	4.95	
B	0.014	0.022	0.356	0.558	
B ₁	0.045	0.070	1.15	1.77	3
C	0.008	0.015	0.204	0.381	
D	0.745	0.840	18.93	21.33	4
D ₁	0.005	—	0.13	—	12
E	0.300	0.325	7.62	8.25	5
E ₁	0.240	0.280	6.10	7.11	6, 7
e	0.100 BSC		2.54 BSC		8
e _A	0.300 BSC		7.62 BSC		9
e _B	—	0.430	—	10.92	10
L	0.115	0.160	2.93	4.06	9
N	16		16		11

92CS-39900

Notes:

1. Refer to JEDEC Publication No. 95 JEDEC Registered and Standard Outlines for Solid State Products, for rules and general information concerning registered and standard outlines, in Section 2.2.
2. Protrusions (flash) on the base plane surface shall not exceed 0.010 in. (0.25 mm).
3. The dimension shown is for full leads. "Half" leads are optional at lead positions

$$1, N, \frac{N}{2}, \frac{N}{2} + 1.$$
4. Dimension D does not include mold flash or protrusions. Mold flash or protrusions shall not exceed 0.010 in. (0.25 mm).
5. E is the dimension to the outside of the leads and is measured with the leads perpendicular to the base plane (zero lead spread).
6. Dimension E₁ does not include mold flash or protrusions.
7. Package body and leads shall be symmetrical around center line shown in end view.
8. Lead spacing e shall be non-cumulative and shall be measured at the lead lip. This measurement shall be made before insertion into gauges, boards or sockets.
9. This is a basic installed dimension. Measurement shall be made with the device installed in the seating plane gauge (JEDEC Outline No. GS-3, seating plane gauge). Leads shall be in true position within 0.010 in. (0.25 mm) diameter for dimension e_A.
10. e_B is the dimension to the outside of the leads and is measured at the lead tips before the device is installed. Negative lead spread is not permitted.
11. N is the maximum number of lead positions.
12. Dimension D₁ at the left end of the package must equal dimension D₁ at the right end of the package within 0.030 in. (0.76 mm).
13. For automatic insertion, any raised irregularity on the top surface (step, mesa, etc.) shall be symmetrical about the lateral and longitudinal package centerlines.

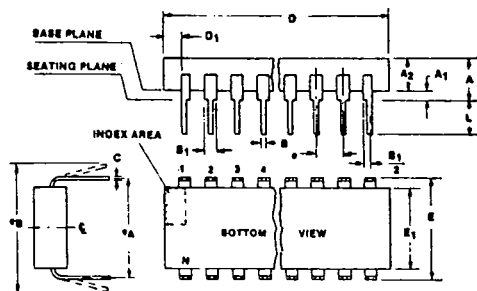
(E) Suffix (JEDEC MS-001-AE)
20-Lead Dual-In-Line Plastic Package

SYMBOL	INCHES		MILLIMETERS		NOTES
	MIN.	MAX.	MIN.	MAX.	
A	—	0.210	—	5.33	9
A ₁	0.015	—	0.39	—	9
A ₂	0.115	0.195	2.93	4.95	
B	0.014	0.022	0.356	0.558	
B ₁	0.045	0.070	1.15	1.77	3
C	0.008	0.015	0.204	0.381	
D	0.925	1.060	23.5	26.9	4
D ₁	0.005	—	0.13	—	12
E	0.300	0.325	7.62	8.25	5
E ₁	0.240	0.280	6.10	7.11	6, 7
e	0.100 BSC		2.54 BSC		8
e _A	0.300 BSC		7.62 BSC		9
e _B	—	0.430	—	10.92	10
L	0.115	0.160	2.93	4.06	9
N	20		20		11

92CS-39997

Dual-In-Line Plastic Packages

T-90-20

(E) Suffix (JEDEC MS-001-AF)
24-Lead Dual-In-Line Plastic Package

SYMBOL	INCHES		MILLIMETERS		NOTES
	MIN.	MAX.	MIN.	MAX.	
A	—	0.210	—	5.33	9
A ₁	0.015	—	0.39	—	9
A ₂	0.115	0.195	2.93	4.95	
B	0.014	0.022	0.356	0.558	
B ₁	0.045	0.070	1.15	1.77	3
C	0.008	0.015	0.204	0.381	
D	1.125	1.275	28.6	32.3	4
D ₁	0.005	—	0.13	—	12
E	0.300	0.325	7.62	8.25	5
E ₁	0.240	0.280	6.10	7.11	6, 7
e	0.100 BSC		2.54 BSC		8
e _A	0.300 BSC		7.62 BSC		9
e _B	—	0.430	—	10.92	10
L	0.115	0.160	2.93	4.06	9
N	24		24		11

92CS-39943

Notes:

1. Refer to JEDEC Publication No. 95 JEDEC Registered and Standard Outlines for Solid State Products, for rules and general information concerning registered and standard outlines, in Section 2.2.
2. Protrusions (flash) on the base plane surface shall not exceed 0.010 in. (0.25 mm).
3. The dimension shown is for full leads. "Half" leads are optional at lead positions

$$1, N, \frac{N}{2}, \frac{N}{2} + 1.$$
4. Dimension D does not include mold flash or protrusions. Mold flash or protrusions shall not exceed 0.010 in. (0.25 mm).
5. E is the dimension to the outside of the leads and is measured with the leads perpendicular to the base plane (zero lead spread).
6. Dimension E₁ does not include mold flash or protrusions.
7. Package body and leads shall be symmetrical around

center line shown in end view.

8. Lead spacing e shall be non-cumulative and shall be measured at the lead tip. This measurement shall be made before insertion into gauges, boards or sockets.
9. This is a basic installed dimension. Measurement shall be made with the device installed in the seating plane gauge (JEDEC Outline No. GS-3, seating plane gauge). Leads shall be in true position within 0.010 in. (0.25 mm) diameter for dimension e_A.
10. e_B is the dimension to the outside of the leads and is measured at the lead tips before the device is installed. Negative lead spread is not permitted.
11. N is the maximum number of lead positions.
12. Dimension D₁ at the left end of the package must equal dimension D₁ at the right end of the package within 0.030 in. (0.76 mm).
13. For automatic insertion, any raised irregularity on the top surface (step, mesa, etc.) shall be symmetrical about the lateral and longitudinal package centerlines.

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